
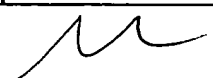




<p align="center"><b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b></p> <p align="center">(PTO-1449)</p> 		<p>ATTY. DOCKET NO. 005199 USA/ Consilium/Consilium</p>	<p>SERIAL NO. 09/725,908</p>
		<p>APPLICANT Yuehshian T. CHI et al.</p>	
		<p>FILING DATE November 30, 2000</p>	<p>GROUP 2141</p>
<p align="center"><b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b></p>			
✓	IslamRaja, M. M., C. Chang, J. P. McVittie, M. A. Cappelli, and K. C. Saraswat. May/June 1993. "Two Precursor Model for Low-Pressure Chemical Vapor Deposition of Silicon Dioxide from Tetraethylorthosilicate." <i>J. Vac. Sci. Technol. B</i> , Vol. 11, No. 3, pp. 720-726.		
✓	Kim, Eui Jung and William N. Gill. July 1994. "Analytical Model for Chemical Vapor Deposition of SiO <sub>2</sub> Films Using Tetraethoxysilane and Ozone" (Abstract). <i>Journal of Crystal Growth</i> , Vol. 140, Issues 3-4, pp. 315-326.		
✓	Guo, R.S, A. Chen, C.L. Tseng, I.K. Fong, A. Yang, C.L. Lee, C.H. Wu, S. Lin, S.J. Huang, Y.C. Lee, S.G. Chang, and M.Y. Lee. June 16-17, 1998. "A Real-Time Equipment Monitoring and Fault Detection System." <i>Semiconductor Manufacturing Technology Workshop</i> , pp. 111-121.		
✓	Lantz, Mikkel. 1999. "Equipment and APC Integration at AMD with Workstream." <i>IEEE</i> , pp. 325-327.		
✓	July 15, 2004. Office Action for U.S. Serial No. 10/172,977, filed June 18, 2002.		
✓	August 2, 2004. Office Action for U.S. Serial No. 10/174,377, filed June 18, 2002.		
✓	August 9, 2004. Written Opinion for PCT Serial No. PCT/US02/19063.		
✓	August 18, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/19116.		
✓	August 24, 2004. Office Action for U.S. Serial No. 10/135,405, filed May 1, 2002.		
✓	August 25, 2004. Office Action for U.S. Serial No. 09/998,384, filed November 30, 2001.		
✓	September 9, 2004. Written Opinion for PCT Serial No. PCT/US02/21942.		
✓	September 16, 2004. International Preliminary Examination Report for PCT Serial No. PCT/US02/24859.		
EXAMINER			<p>DATE CONSIDERED 11/19/04</p>

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)

ATTY. DOCKET NO.  
005199 USA/  
Consilium/Consilium

SERIAL NO.  
09/725,908

APPLICANT  
Yuehshian T. CHI et al.



FILING DATE  
November 30, 2000

GROUP  
2152


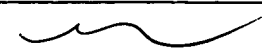
## U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
✓	4,957,605	09/18/90	Hurwitt et al.			04/17/89
✓	5,240,552	08/31/93	Yu et al.			12/11/91
✓	5,369,544	11/29/94	Mastrangelo			04/05/93
✓	5,444,837	08/22/95	Bomans et al.			12/29/93
✓	5,665,214	09/09/97	Iturralde			05/03/95
✓	5,695,810	12/09/97	Dubin et al.			11/20/96
✓	5,824,599	10/20/98	Schacham-Diamand et al.			01/16/96
✓	5,825,356	10/20/98	Habib et al.			03/18/96
✓	5,831,851	11/03/98	Eastburn et al.			03/21/95
✓	5,838,951	11/17/98	Song			08/28/96
✓	5,859,777	01/12/99	Yokoyama et al.			05/13/97
✓	5,871,805	02/16/99	Lemelson			04/08/96
✓	5,943,550	08/24/99	Fulford, Jr. et al.			03/29/96
✓	6,012,048	01/04/00	Gustin et al.			05/30/97
✓	6,037,664	03/14/00	Zhao et al.			03/31/98
✓	6,059,636	05/09/00	Inaba et al.			07/09/98
✓	6,096,649	08/01/00	Jang			10/25/99
✓	6,100,195	08/08/00	Chan et al.			12/28/98
✓	6,114,238	09/05/00	Liao			05/20/98
✓	6,150,270	11/21/00	Matsuda et al.			01/07/99
✓	6,157,864	12/05/00	Schwenke et al.			05/08/98
✓	6,181,013 B1	01/30/01	Liu et al.			03/13/00
✓	6,212,961 B1	04/10/01	Dvir			02/11/99
✓	6,226,563 B1	05/01/01	Lim			09/04/98
✓	6,228,280 B1	05/08/01	Li et al.			05/06/98
✓	6,237,050 B1	05/22/01	Kim et al.			09/04/98
✓	2001/0006873 A1	07/05/01	Moore			02/13/01
✓	6,259,160 B1	07/10/01	Lopatin et al.			04/21/99
✓	6,281,127 B1	08/28/01	Shue			04/15/99
EXAMINER			DATE CONSIDERED 11/19/04			

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				APPLICANT Yuehshian T. CHI et al.			
				FILING DATE November 30, 2000		GROUP 2152	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
✓	6,317,643 B1	11/13/01	Dmochowski			03/31/99	
✓	6,339,727 B1	01/15/02	Ladd			12/21/98	
✓	6,355,559 B1	03/12/02	Havemann et al.			11/03/00	
✓	6,391,780 B1	05/21/02	Shih et al.			08/23/99	
✓	6,417,014 B1	07/09/02	Lam et al.			10/19/99	
✓	6,427,093 B1	07/30/02	Toprac			10/07/99	
✓	6,432,728 B1	08/13/02	Tai et al.			10/16/00	
✓	6,449,524 B1	09/10/02	Miller et al.			01/04/00	
✓	6,455,415 B1	09/24/02	Lopatin et al.			04/16/01	
✓	2002/0165636 A1	11/07/02	Hasan			04/24/02	
✓	6,484,064 B1	11/19/02	Campbell			10/05/99	
✓	6,495,452 B1	12/17/02	Shih			08/18/99	
✓	2002/0193899 A1	12/19/02	Shanmugasundram et al.			05/01/02	
✓	2003/0017256 A1	01/23/03	Shimane			06/12/02	
✓	6,515,368 B1	02/04/03	Lopatin et al.			12/07/01	
✓	6,517,414 B1	02/11/03	Tobin et al.			03/10/00	
✓	6,528,409 B1	03/04/03	Lopatin et al.			04/29/02	
✓	6,537,912 B1	03/25/03	Agarwal			08/25/00	
✓	6,580,958 B1	06/17/03	Takano			11/22/99	
✓	6,605,549 B2	08/12/03	Leu et al.			09/29/01	
✓	6,607,976 B2	08/19/03	Chen et al.			09/25/01	
✓	6,609,946 B1	08/26/03	Tran			07/14/00	
✓	6,616,513 B1	09/09/03	Osterheld			04/05/01	
✓	6,624,075 B1	09/23/03	Lopatin et al.			11/05/02	
✓	6,630,741 B1	10/07/03	Lopatin et al.			12/07/01	
✓	6,660,633 B1	12/09/03	Lopatin et al.			02/26/02	
✓	6,708,074 B1	03/16/04	Chi et al.			08/11/00	
✓	6,708,075 B2	03/16/04	Sonderman et al.			11/16/01	
✓	6,728,587 B2	04/27/04	Goldman et al.			12/27/00	
EXAMINER 			DATE CONSIDERED 11/19/00				

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				APPLICANT Yuehshian T. CHI et al.			
				FILING DATE November 30, 2000		GROUP 2152	
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
✓	EP 0 932 195 A1	07/28/99	EP			X	
✓	EP 1 083 470 A2	03/14/01	EP			X	
✓	GB 2 365 215 A	02/13/02	GB			X	
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
✓	Sun, S.C. 1998. "CVD and PVD Transition Metal Nitrides as Diffusion Barriers for Cu Metallization." <i>IEEE</i> . pp. 243-246.						
✓	Tagami, M., A. Furuya, T. Onodera, and Y. Hayashi. 1999. "Layered Ta-nitrides (LTN) Barrier Film by Power Swing Sputtering (PSS) Technique for MOCVD-Cu Damascene Interconnects." <i>IEEE</i> . pp. 635-638.						
✓	Yamagishi, H., Z. Tokei, G.P. Beyer, R. Donaton, H. Bender, T. Nogami, and K. Maex. 2000. "TEM/SEM Investigation and Electrical Evaluation of a Bottomless I-PVD TA(N) Barrier in Dual Damascene" (Abstract). <i>Advanced Metallization Conference 2000</i> . San Diego, CA.						
✓	Eisenbraun, Eric, Oscar van der Straten, Yu Zhu, Katharine Dovidenko, and Alain Kaloyeros. 2001. "Atomic Layer Deposition (ALD) of Tantalum-Based Materials for Zero Thickness Copper Barrier Applications" (Abstract). <i>IEEE</i> . pp. 207-209.						
✓	Smith, S.R., K.E. Elers, T. Jacobs, V. Blaschke, and K. Pfeifer. 2001. "Physical and Electrical Characterization of ALD Tin Used as a Copper Diffusion Barrier in 0.25 μm, Dual Damascene Backend Structures" (Abstract). <i>Advanced Metallization Conference 2001</i> . Montreal, Quebec.						
✓	Kim, Y.T. and H. Sim. 2002. "Characteristics of Pulse Plasma Enhanced Atomic Layer Deposition of Tungsten Nitride Diffusion Barrier for Copper Interconnect" (Abstract). <i>IEIC Technical Report</i> . Vol. 102, No. 178, pp. 115-118.						
✓	Elers, Kai-Erik, Ville Saanila, Pekka J. Soininen, Wei-Min Li, Juhana T. Kostamo, Suvi Haukka, Jyrki Juhanoja, and Wim F.A. Besling. 2002. "Diffusion Barrier Deposition on a Copper Surface by Atomic Layer Deposition" (Abstract). <i>Advanced Materials</i> . Vol. 14, No. 13-14, pp. 149-153.						
✓	Peng, C.H., C.H. Hsieh, C.L. Huang, J.C. Lin, M.H. Tsai, M.W. Lin, C.L. Chang, Winston S. Shue, and M.S. Liang. 2002. "A 90nm Generation Copper Dual Damascene Technology with ALD TaN Barrier." <i>IEEE</i> . pp. 603-606.						
✓	Van der Straten, O., Y. Zhu, E. Eisenbraun, and A. Kaloyeros. 2002. "Thermal and Electrical Barrier Performance Testing of Ultrathin Atomic Layer Deposition Tantalum-Based Materials for Nanoscale Copper Metallization." <i>IEEE</i> . pp. 188-190.						
✓	Wu, Z.C., Y.C. Lu, C.C. Chiang, M.C. Chen, B.T. Chen, G.J. Wang, Y.T. Chen, J.L. Huang, S.M. Jang, and M.S. Liang. 2002. "Advanced Metal Barrier Free Cu Damascene Interconnects with PECVD Silicon Carbide Barriers for 90/65-nm BEOL Technology." <i>IEEE</i> . pp. 595-598.						
✓	July 25, 2003. International Search Report for PCT/US02/24858.						
✓	March 30, 2004. Written Opinion for PCT/US02/19062.						
✓	April 9, 2004. Written Opinion for PCT/US02/19116.						
✓	April 22, 2004. Office Action for U.S. Serial No. 09/998,372, filed November 30, 2001.						
EXAMINER 				DATE CONSIDERED 11/19/04			

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INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION

(PTO-1449)



ATTY. DOCKET NO.  
005199  
USA/Consilium/Consilium

SERIAL NO.  
09/725,908

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MAR 30 2004

APPLICANT  
Yuehshian T. CHI et al. Technology Center 2100



FILING DATE  
November 30, 2000

GROUP  
2152

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
/	4,901,218	02/13/90	Cornwell			03/04/88
/	5,427,878	06/27/95	Corliss			05/16/94
/	5,761,065	06/02/98	Kittler et al.			03/30/95
/	5,862,054	01/19/99	Li			02/20/97
/	5,912,678	06/15/99	Saxena et al.			04/14/97
/	5,926,690	07/20/99	Toprac et al.			05/28/97
/	6,074,443	06/13/00	Venkatesh et al.			01/29/98
/	6,111,634	08/29/00	Pecen et al.			05/28/97
/	6,150,664	11/21/00	Su			06/29/99
/	6,245,581 B1	06/12/01	Bonser et al.			04/19/00
/	2001/0044667 A1	11/22/01	Nakano et al.			05/16/01
/	6,346,426 B1	02/12/02	Toprac et al.			11/17/00
/	6,363,294 B1	03/26/02	Coronel et al.			12/29/98
/	6,442,496 B1	08/27/02	Pasadyn et al.			08/08/00
/	6,486,492 B1	11/26/02	Su			11/20/00
/	6,492,281 B1	12/10/02	Song et al.			09/22/00
/	6,540,591 B1	04/01/03	Pasadyn et al.			04/18/01
/	6,560,504 B1	05/06/03	Goodwin et al.			09/29/99
/	6,590,179 B2	07/08/03	Tanaka et al.			02/26/01
/	6,604,012 B1	08/05/03	Cho et al.			08/23/00
/	6,618,692 B2	09/09/03	Takahashi et al.			02/26/01
/	6,625,497 B2	09/23/03	Fairbairn et al.			07/10/01
/	6,640,151 B1	10/28/03	Somekh et al.			12/22/99
EXAMINER 				DATE CONSIDERED 11/17/04		

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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  (PTO-1449)				ATTY. DOCKET NO. 005199 USA/Consilium/Consilium		SERIAL NO. 09/725,908  <b>RECEIVED</b>  MAR 30 2004	
				APPLICANT Yuehshian T. CHI et al.		Technology Center 2100	
				FILING DATE November 30, 2000		GROUP 2152	
<b>FOREIGN PATENT DOCUMENTS</b>							
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						Yes	No
/	0 397 924 A1	11/22/90	Europe			X	
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
/	Rocha, Joao and Carlos Ramos. September 12, 1994. "Task Planning for Flexible and Agile Manufacturing Systems." <i>Intelligent Robots and Systems '94. Advanced Robotic Systems and the Real World, IROS '94. Proceedings of the IEEE/RSJ/GI International Conference on Munich, Germany 12-16 Sept. 1994.</i> New York, New York: IEEE. pp. 105-112.						
/	March 15, 2002. Office Action for U.S. Serial No. 09/469,227, filed December 22, 1999.						
/	March 29, 2002. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.						
/	June 20, 2002. Office Action for U.S. Serial No. 09/619,044, filed July 19, 2000.						
/	September 26, 2002. Office Action for U.S. Serial No. 09/637,620, filed August 11, 2000.						
/	October 23, 2002. Office Action for U.S. Serial No. 09/469,227, filed December 22, 1999.						
/	December 17, 2002. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.						
/	February 10, 2003. Office Action for U.S. Serial No. 09/619,044, filed July 19, 2000.						
/	April 9, 2003. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.						
/	May 8, 2003. Office Action for U.S. Serial No. 09/637,620, filed August 11, 2000.						
/	June 18, 2003. Office Action for U.S. Serial No. 09/655,542, filed September 6, 2000.						
/	August 8, 2003. International Search Report for PCT/US03/08513.						
/	August 25, 2003. Office Action for U.S. Serial No. 10/100,184, filed March 19, 2002.						
/	September 15, 2003. Office Action for U.S. Serial No. 09/928,474, filed August 14, 2001.						
/	November 5, 2003. Office Action for U.S. Serial No. 10/172,977, filed June 18, 2002.						
/	December 1, 2003. Office Action for U.S. Serial No. 10/173,108, filed June 18, 2002.						
/	December 11, 2003. Office Action for U.S. Serial No. 09/943,383, filed August 31, 2001.						
/	December 16, 2003. International Search Report for PCT/US03/23964.						
/	January 20, 2004. Office Action for U.S. Serial No. 09/927,444, filed August 13, 2001.						
/	January 23, 2004. International Search Report for PCT/US02/24860.						
/	February 2, 2004. Office Action for U.S. Serial No. 09/363,966, filed July 29, 1999.						
EXAMINER  				DATE CONSIDERED  11/17/06			

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INFORMATION DISCLOSURE  
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005199  
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DEC 19 2003

APPLICANT  
Yuehshian T. CHI et al.

Technology Center 2100

FILING DATE  
November 30, 2000

GROUP  
2152

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
~	4,207,520	06/10/80	Flora et al.			04/06/78
✓	4,209,744	06/24/80	Gerasimov et al.			03/27/78
~	4,609,870	09/02/86	Lale et al.			09/13/84
✓	4,755,753	07/05/88	Chern			07/23/86
~	5,427,878	06/27/95	Corliss			05/16/94
✓	5,534,289	07/09/96	Bilder et al.			01/03/95
✓	5,867,389	02/02/99	Hamada et al.			11/26/96
✓	6,041,263	03/21/00	Boston et al.			10/01/97
~	6,077,412	06/20/00	Ting et al.			10/30/98
~	6,271,670	08/07/01	Caffey			02/08/99
✓	6,400,162	06/04/02	Mallory et al.			07/21/00
✓	US 2002/0077031	06/20/02	Johansson et al.			07/06/01
✓	6,442,496	08/27/02	Pasady et al.			08/08/00
✓	6,563,308	05/13/03	Nagano et al.			03/27/01
✓	6,587,744	07/01/03	Stoddard et al.			06/20/00

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
✓	WO 01/11679	02/15/01	WIPO			X	
~	WO 01/080306	10/25/01	WIPO			X	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

✓	Miller, G. L., D. A. H. Robinson, and J. D. Wiley. July 1976. "Contactless measurement of semiconductor conductivity by radio frequency-free-carrier power absorption." <i>Rev. Sci. Instrum.</i> , Volume 47, No. 7. pp. 799 - 805.
✓	1999. "Contactless Bulk Resistivity/Sheet Resistance Measurement and Mapping Systems." <a href="http://www.Lehighton.com/fabtech1/index.html">www.Lehighton.com/fabtech1/index.html</a> .
✓	2000. "Microsense II Capacitance Gaging System." <a href="http://www.adetech.com">www.adetech.com</a> .

EXAMINER

*[Signature]*

DATE CONSIDERED

11/19/06

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		APPLICANT Yuehshian T. CHI et al.					
		FILING DATE November 30, 2000		GROUP 2152			
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." <i>J. Vac. Sci. Technol.</i> Volume 18, No. 4, pp. 1287 - 1296. ✓						
	March 5, 2001. "KLA-Tencor Introduces First Production-worthy Copper CMP In-situ Film Thickness and End-point Control System." <a href="http://www.kla-tencor.com/j/servlet/NewsItem?newsItemID=74">http://www.kla-tencor.com/j/servlet/NewsItem?newsItemID=74</a> . ✓						
	2002. "Microsense II - 5810: Non-Contact Capacitance Gaging Module." <a href="http://www.adetech.com">www.adetech.com</a> . ✓						
	08 August 2003. PCT International Search Report from PCT/US03/08513. ✓						
	14 October 2003. PCT International Search Report from PCT/US02/21942. ✓						
	20 October 2003. PCT International Search Report from PCT/US02/19116. ✓						
	23 October 2003. PCT International Preliminary Examination Report from PCT/US01/24910. ✓						
	"NanoMapper wafer nanotopography measurement by ADE Phase Shift." <a href="http://www.phase-shift.com/nanomap.shtml">http://www.phase-shift.com/nanomap.shtml</a> . ✓						
	"Wafer flatness measurement of advanced wafers." <a href="http://www.phase-shift.com/wafer-flatness.shtml">http://www.phase-shift.com/wafer-flatness.shtml</a> . ✓						
	"ADE Technologies, Inc. - 6360." <a href="http://www.adetech.com/6360.shtml">http://www.adetech.com/6360.shtml</a> . ✓						
	"3D optical profilometer MicroXAM by ADE Phase Shift." <a href="http://www.phase-shift.com/microxam.shtml">http://www.phase-shift.com/microxam.shtml</a> . ✓						
	"NanoMapper FA factory automation wafer nanotopography measurement." <a href="http://www.phase-shift.com/nanomapperfa.shtml">http://www.phase-shift.com/nanomapperfa.shtml</a> . ✓						
EXAMINER			DATE CONSIDERED				
11/19/06			✓				

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.